



Preliminary Datasheet



Features

- SMD filter consisting of coupled resonators with stepped impedances
- MgTiO₃ - CaTiO₃ ($\epsilon_f = 21$ / $TC_f = 0 \pm 10$ ppm/K) with a coating of copper (10 μ m) and tin (>5 μ m)
- Excellent reflow solderability, no migration effect due to copper/tin metallization

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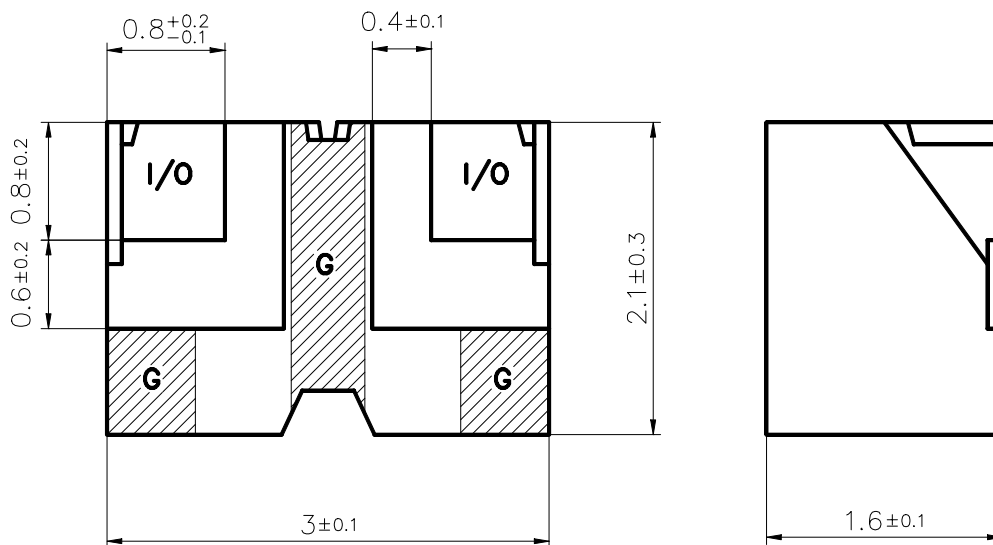
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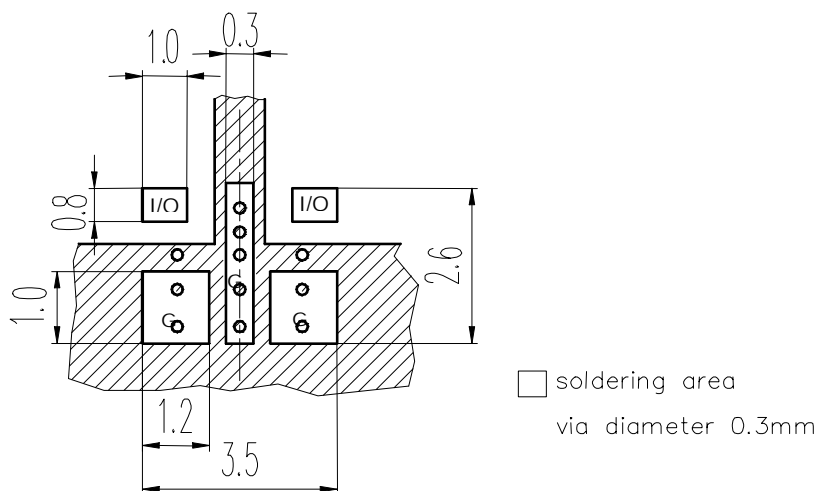


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Component drawing



Recommended footprint



FOOTPRINT_010601.DWG→WMF

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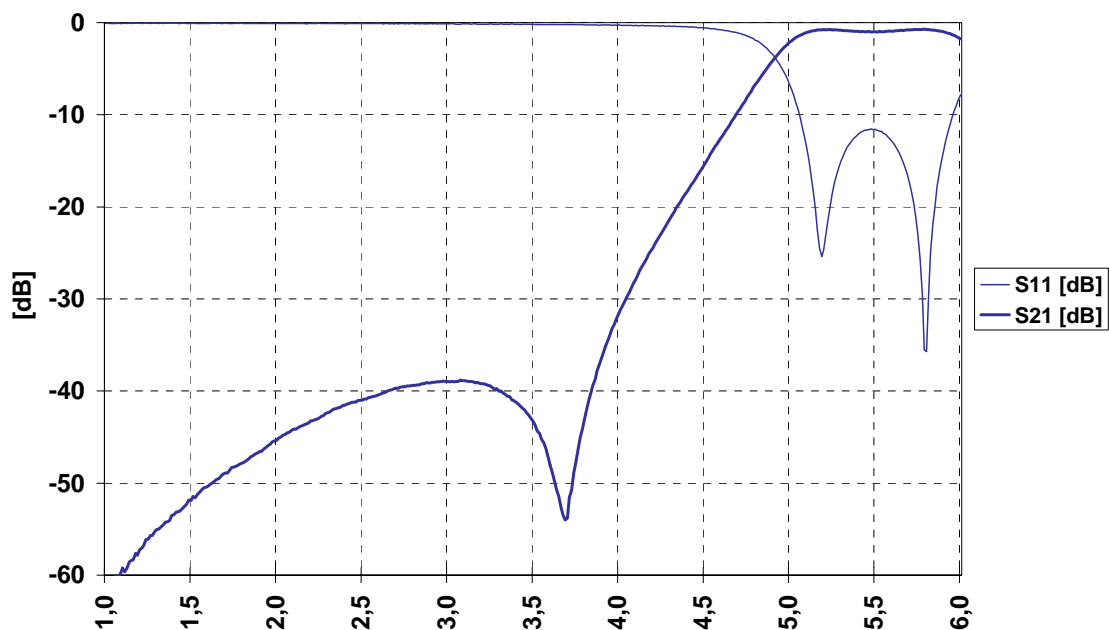
Characteristics

		min.	typ.	max.	
Center frequency	f_c			5.5	GHz
Insertion loss [5150 – 5850] MHz	α_{IL}		1.0	1.4	dB
Passband [5150 – 5850] MHz	B	700			MHz
Amplitude ripple (peak - peak) [5150 – 5850] MHz	$\Delta\alpha$				dB
Standing wave ratio [5150 – 5850] MHz	SWR		1.8	2.0	
Impedance	Z		50		Ω
Power	P			1.0	W
Attenuation		at DC to 1990 MHz	45	50	dB
		at 1990 to 2170 MHz	42	45	dB
		at 2400 to 2500 MHz	40	43	dB

Maximum ratings

IEC climatic category (IEC 68-1)		- 40/+ 90/56	
Operating temperature	T_{Op}	-40 / +85	°C

Typical passband characteristic





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Processing information

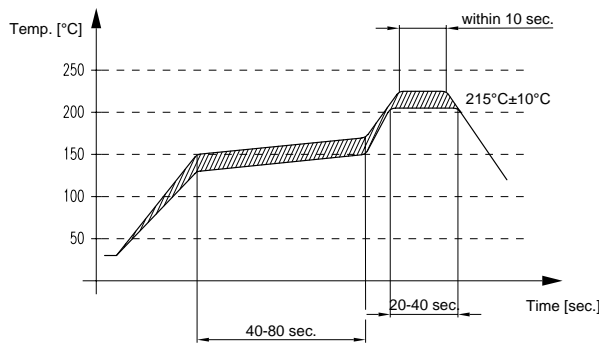
ZNr.: 577 (FILT95_2)

- Wettability to IEC 68-2-58: $\geq 75\%$ (after aging)

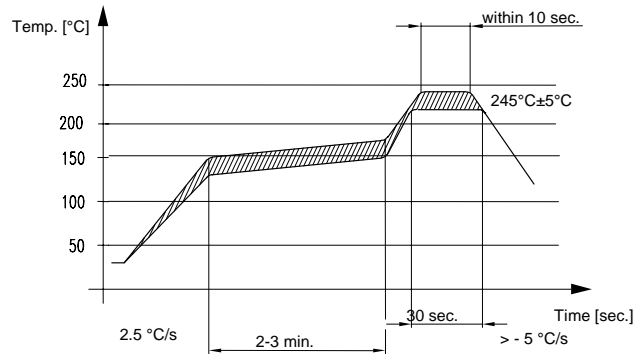
Soldering requirements

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	°C °C

Recommended soldering conditions (infrared):



eutectic SnPb solder paste profile



leadfree solder paste profile

Delivery mode

- Blister tape acc. to IEC 286-3, PS, grey
- Pieces/tape: t.b.d.

t.b.d.

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The information contained in this data sheet describes the type of component and shall not be considered as guaranteed characteristics. Purchase orders are subject to the General Conditions for the Supply of Products and Services of the Electrical and Electronics Industry recommended by the ZVEI (German Electrical and Electronic Manufacturers' Association), unless otherwise agreed.

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